

[ABSTRACT]

The present invention is a wiring board (100) with a multi-layer structure having a plurality of build-up layers (1), wherein, among the build-up layers (1), a build-up layer (3) on a front surface side formed last has a first solder pad (61) and a second solder pad (62), a solder resist layer (4) is provided on the front surface side of the build-up layer (3) on a front surface side, and heights of the first solder pad (61) and the second solder pad (62) from front surfaces thereof to a front surface of the solder resist layer (4) are different from each other.